



General Description

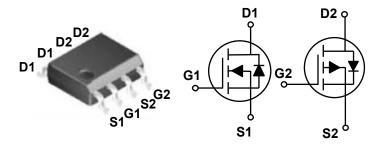
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	Ι _D
60 V	36 mΩ	12.5 A
-60 V	70 mΩ	-9.7 A

Features

- Fast Switching
- · Green Device Available

SOP-8 Pin Configuration



Applications

- · Boost Driver
- · Brushless Motor

Absolute Maximu	bsolute Maximum Ratings T _c =25°C unless otherwise noted								
Symbol	Parameter		Rating						
V_{DS}	Drain-Source Voltage	60	-60	V					
V_{GS}	Gate-Source Voltage	±2	0 ±20	V					
I _D	Drain Current - Continuous (T _A =25°C)	12.	5 -9.7	Α					
I _{DM}	Drain Current - Pulsed (NOTE 1)	37.	5 -22.5	Α					
P_{D}	Power Dissipation (T _A =25°C)		1.47						
T_J	Operating Junction Temperature Range	-	-55 to 150						
T _{STG}	Storage Temperature Range	-	-55 to 150						
Marking Code		BG03	86 , AP10G06S						

Thermal Characteristics					
Symbol	Parameter	Rating	Unit		
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	85	°C/W		





N Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} =10V , I_D =4A			36	mΩ
		V_{GS} =4.5V , I_D =2A			38	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250uA$	1.2		2.5	V
gfs	Forward Transconductance	V_{DS} =5V , I_{D} =4A		21		S

Dynamic and Switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge			12.6		
Q_gs	Gate-Source Charge	V_{DS} =48V , V_{GS} =4.5V , I_{D} =4A	-	3.2		nC
Q_{gd}	Gate-Drain Charge		-	6.3		
$T_{d(on)}$	Turn-On Delay Time		-	8		
T _r	Rise Time	V_{DD} =30V , V_{GS} =10V , R_{G} =3.3 Ω		14.2		nS
$T_{d(off)}$	Turn-Off Delay Time	, I _D =4A		24.4		113
T_f	Fall Time	1 [4.6		
C _{iss}	Input Capacitance			1378		
C _{oss}	Output Capacitance	V_{DS} =15V , V_{GS} =0V , F=1MHz		86		pF
C_{rss}	Reverse Transfer Capacitance		-	64		
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , F=1MHz		3.2		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			4.8	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =1A			1.2	V

NOTES:

- 1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
- 2. The data tested by pulsed, pulse width \leq 300us, duty cycle \leq 2%.
- 3. Essentially independent of operating temperature.



S8MBG036



60V N+P Dual Channel MOSFETs

Characteristics Curves

FIG. 1-Forward Characteristics of Body Diode

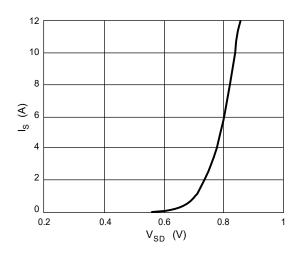


FIG. 2-Normalized $V_{GS(th)}$ vs T_J

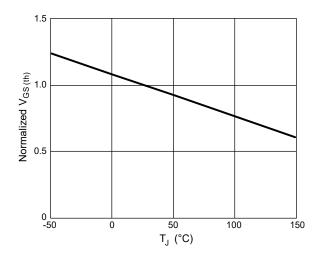


FIG. 2-Normalized $R_{DS(ON)}$ vs T_J

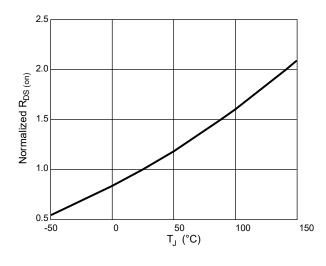


FIG. 4-Gate Charge Characteristics

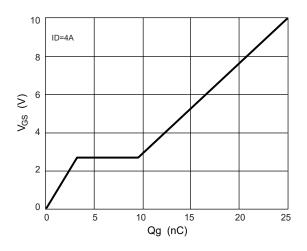


FIG. 5-Safe Operation Area

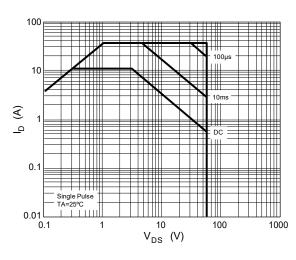
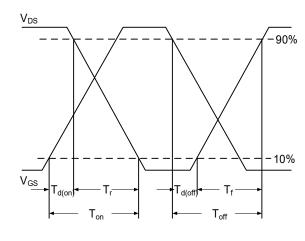


FIG. 6-Switching Time Waveform







P Channel Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V , I _D = -250uA	-60			V
I _{DSS}	Drain-Source Leakage Current	V_{DS} = -48V , V_{GS} = 0V			-1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = ±20V , V_{DS} = 0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	IStatic Drain-Source On-Resistance	V_{GS} = -10V , I_D = -3A			70	mΩ
		V_{GS} = -4.5V , I_D = -2A			85	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250uA$	-1.2		-2.5	V
gfs	Forward Transconductance	V_{DS} = -5V , I_{D} = -3A		15		S

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Q_g	Total Gate Charge	\/ - 49\/ \/ - 45\/		9.86		
Q_gs	Gate-Source Charge	V _{DS} = -48V , V _{GS} = -4.5V , I _D = -3A	-	3.1		nC
Q_{gd}	Gate-Drain Charge	-1 _D - 3, t		2.95		
$T_{d(on)}$	Turn-On Delay Time		-	28.8		
T_r	Rise Time	V_{DD} = -15V , V_{GS} = -10V ,		19.8		nS
$T_{d(off)}$	Turn-Off Delay Time	$R_G = 3.3\Omega$, $I_D = -1A$	-	60.8		113
T_f	Fall Time	Ι Γ		7.2		
C_{iss}	Input Capacitance	V _{DS} = -15V , V _{GS} = 0V , F= 1MHz		1447		
C _{oss}	Output Capacitance			97.3		pF
C_{rss}	Reverse Transfer Capacitance			70		
R_g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , F=1MHz		13.5		Ω

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V _G =V _D =0V , Force Current			-3.7	Α
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S = -1A			-1.2	V

NOTES:

- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. Essentially independent of operating temperature.



S8MBG036



60V N+P Dual Channel MOSFETs

Characteristics Curves

FIG. 7-Forward Characteristics of Body Diode

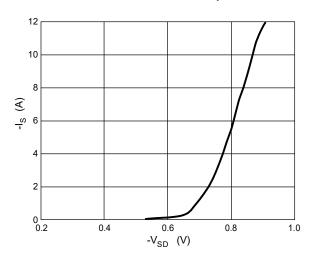


FIG. 8-Normalized V_{GS(th)} vs T_J

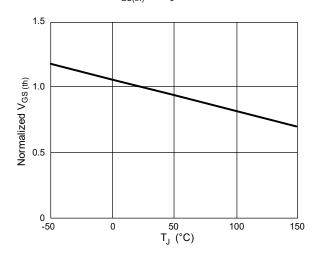


FIG. 9-Normalized $R_{\text{DS}(\text{ON})}\,\text{vs}\;T_{\text{J}}$

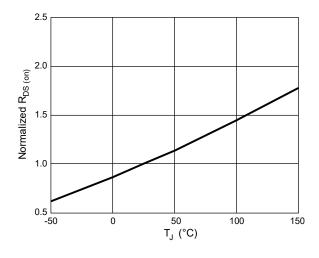


FIG. 10-Gate Charge Characteristics

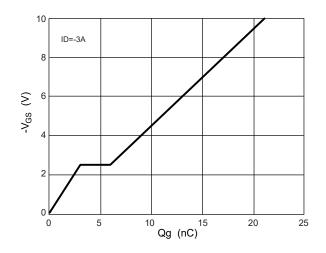


FIG. 11-Safe Operation Area

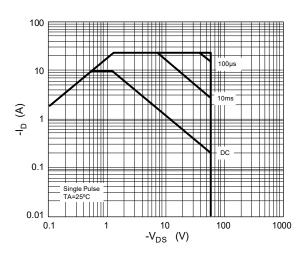
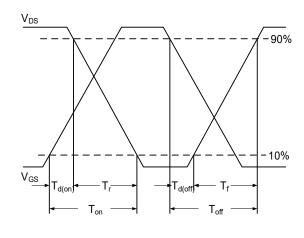


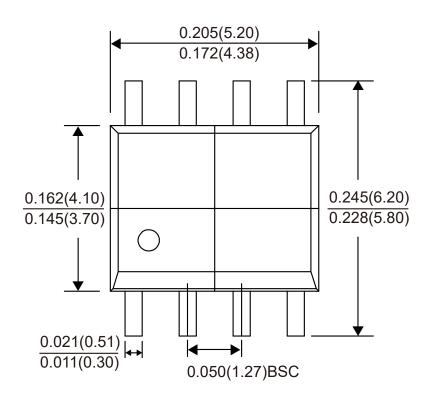
FIG. 12-Switching Time Waveform

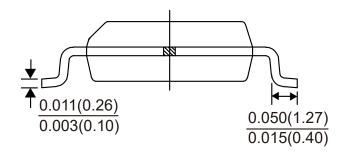


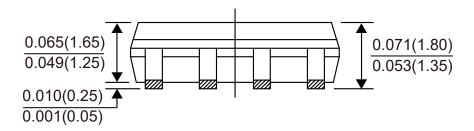




Package Outline Dimensions







SOP-8Dimensions in inches and (millimeters)





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